

**INTEGRATED INTERCONNECT AND METHOD  
OF MANUFACTURE THEREFOR  
ABSTRACT OF THE DISCLOSURE**

An integrated interface structure for a nested body to provide an  
5 electrical connection. The interface structure includes nested bond pads which  
electrically interface with leads. The nested bond pads are fabricated on a  
microstructure to provide an interface to drive circuitry for transducer elements  
of a slider or head supported by the microstructure.

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